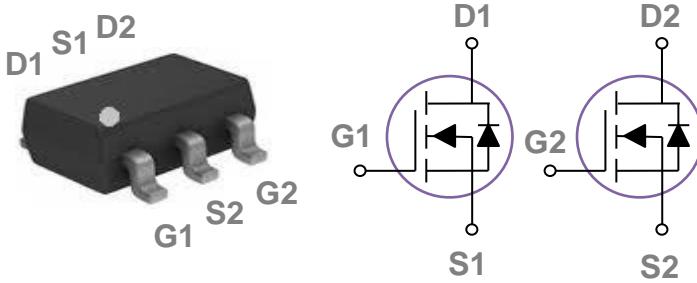


General Description

These dual N Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

SOT23-6 Dual Pin Configuration



BVDSS	RDS(ON)	ID
20V	53mΩ	3.6A

Features

- 20V, 3.6A, $RDS(ON) = 53m\Omega$ @ $VGS = 4.5V$
- Improved dv/dt capability
- Fast switching
- Green Device Available
- Suit for 1.8V Gate Drive Applications

Applications

- Notebook
- Load Switch
- Hand-Held Instruments

Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-Source Voltage	± 10	V
I_D	Drain Current – Continuous ($T_A=25^\circ C$)	3.6	A
	Drain Current – Continuous ($T_A=70^\circ C$)	2.9	A
I_{DM}	Drain Current – Pulsed ¹	14.4	A
P_D	Power Dissipation ($T_A=25^\circ C$)	1.25	W
	Power Dissipation – Derate above 25°C	0.01	W/°C
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	100	°C/W

Electrical Characteristics ($T_J=25\text{ }^{\circ}\text{C}$, unless otherwise noted)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	20	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to $25\text{ }^{\circ}\text{C}$, $I_D=1\text{mA}$	---	0.02	---	$\text{V}/\text{ }^{\circ}\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=20\text{V}$, $V_{GS}=0\text{V}$, $T_J=25\text{ }^{\circ}\text{C}$	---	---	1	μA
		$V_{DS}=16\text{V}$, $V_{GS}=0\text{V}$, $T_J=125\text{ }^{\circ}\text{C}$	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 10\text{V}$, $V_{DS}=0\text{V}$	---	---	± 100	nA

On Characteristics

$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=4.5\text{V}$, $I_D=3\text{A}$	---	44	53	$\text{m}\Omega$
		$V_{GS}=2.5\text{V}$, $I_D=2\text{A}$	---	60	75	
		$V_{GS}=1.8\text{V}$, $I_D=1\text{A}$	---	85	110	
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D = 250\mu\text{A}$	0.3	0.5	1	V
$\Delta V_{GS(\text{th})}$	$V_{GS(\text{th})}$ Temperature Coefficient		---	-2	---	$\text{mV}/\text{ }^{\circ}\text{C}$
g_{fs}	Forward Transconductance	$V_{DS}=10\text{V}$, $I_S=1\text{A}$	---	2	---	S

Dynamic and switching Characteristics

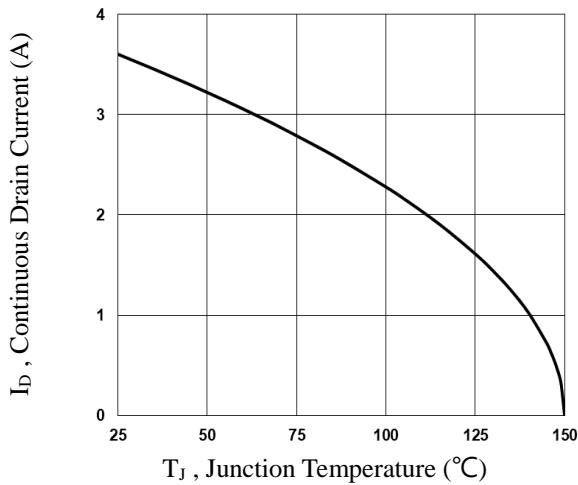
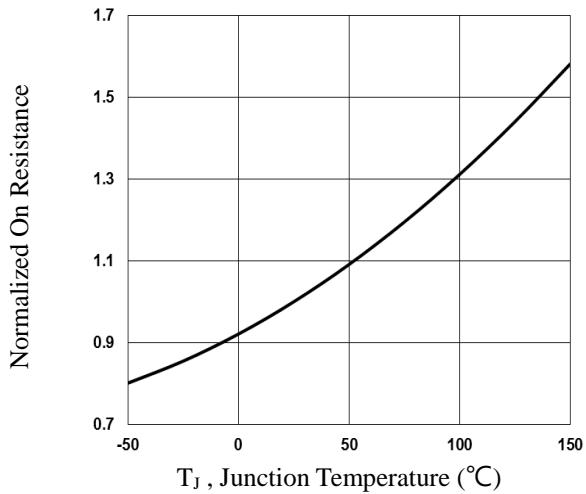
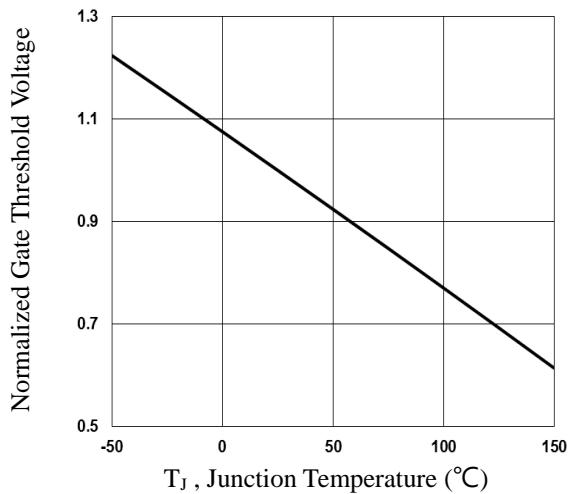
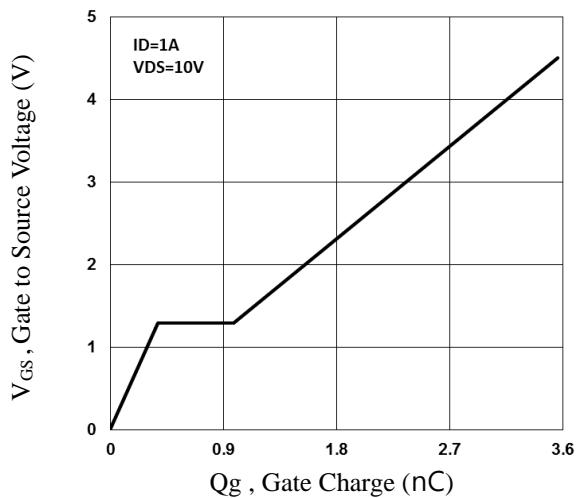
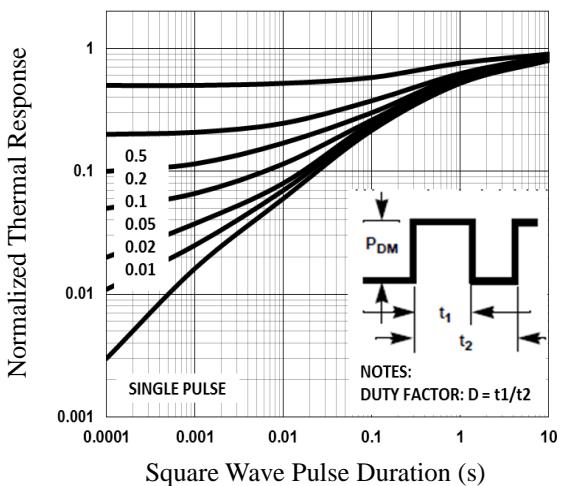
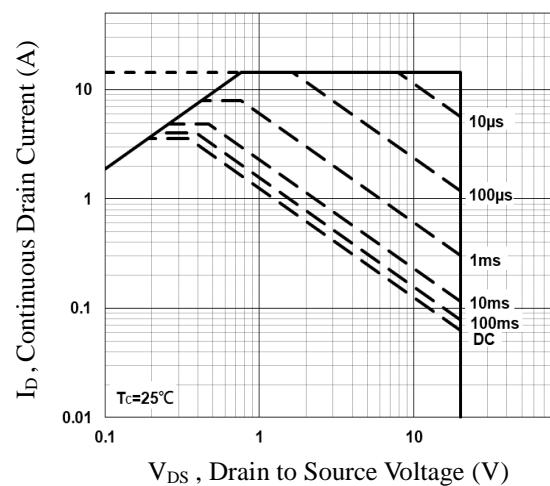
Q_g	Total Gate Charge ^{2, 3}	$V_{DS}=10\text{V}$, $V_{GS}=4.5\text{V}$, $I_D=1\text{A}$	---	3.6	7.2	nC
Q_{gs}	Gate-Source Charge ^{2, 3}		---	0.38	0.76	
Q_{gd}	Gate-Drain Charge ^{2, 3}		---	0.6	1.2	
$T_{d(on)}$	Turn-On Delay Time ^{2, 3}	$V_{DD}=10\text{V}$, $V_{GS}=4.5\text{V}$, $R_G=25\Omega$ $I_D=1\text{A}$	---	1.8	5	nS
T_r	Rise Time ^{2, 3}		---	5.6	12	
$T_{d(off)}$	Turn-Off Delay Time ^{2, 3}		---	11.3	24	
T_f	Fall Time ^{2, 3}		---	3.2	7	
C_{iss}	Input Capacitance	$V_{DS}=15\text{V}$, $V_{GS}=0\text{V}$, $F=1\text{MHz}$	---	180	360	pF
C_{oss}	Output Capacitance		---	32	64	
C_{rss}	Reverse Transfer Capacitance		---	26	52	

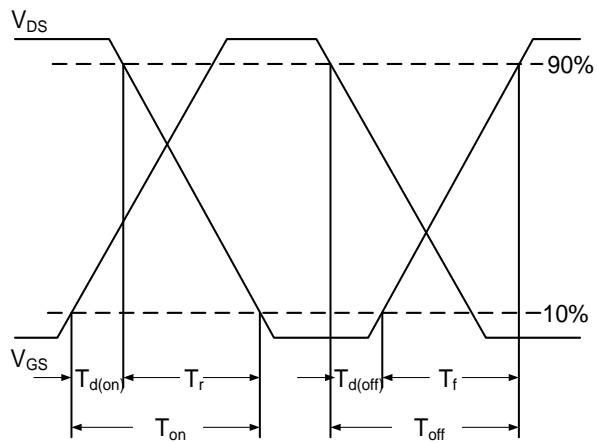
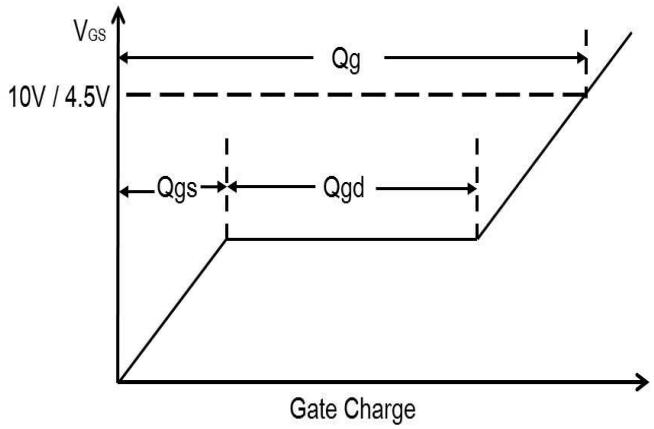
Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	3.6	A
I_{SM}	Pulsed Source Current		---	---	7.2	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_s=1\text{A}$, $T_J=25\text{ }^{\circ}\text{C}$	---	---	1	V

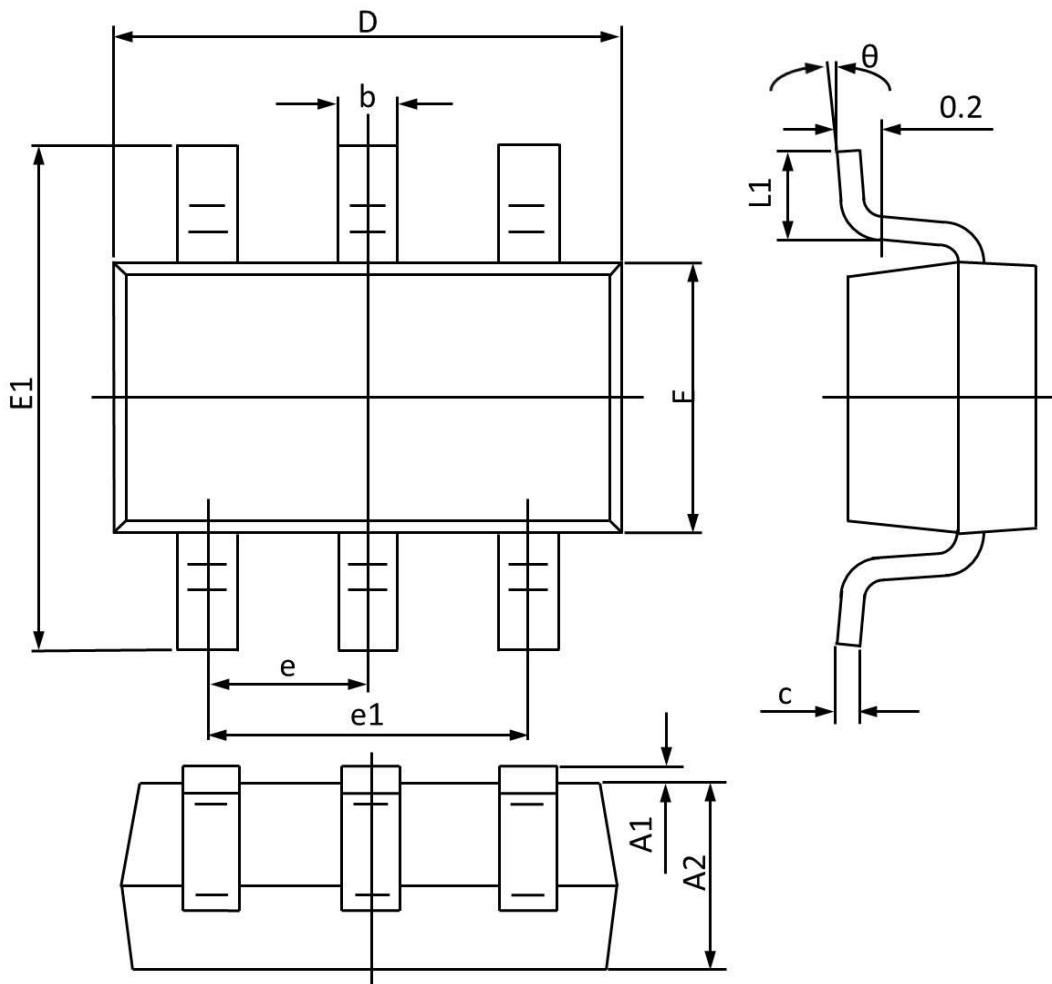
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.


Fig.1 Continuous Drain Current vs. T_J

Fig.2 Normalized RD_{SON} vs. T_J

Fig.3 Normalized V_{th} vs. T_J

Fig.4 Gate Charge Waveform

Fig.5 Normalized Transient Impedance

Fig.6 Maximum Safe Operation Area


Fig.7 Switching Time Waveform

Fig.8 Gate Charge Waveform

SOT23-6 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A1	---	0.150	---	0.006
A2	0.900	1.300	0.035	0.051
b	0.300	0.500	0.012	0.019
c	0.100	0.200	0.004	0.008
D	2.800	3.050	0.110	0.120
E1	2.600	3.000	0.103	0.118
F	1.500	1.800	0.059	0.071
e	0.950 TYP		0.037 TYP	
e1	1.900 TYP		0.075 TYP	
L1	0.250	0.600	0.010	0.024
θ	0°	8°	0°	8°

SOT23-6 RECOMMENDED LAND PATTERN

